

01-11-2005



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OFFICE

IN THE UNITED STATES

12-22-04

Applicant: Cheng-Lien Chiang  
Assignee: Bridge Semiconductor Corporation  
Title: THREE-DIMENSIONAL STACKED SEMICONDUCTOR  
PACKAGE WITH CHIPS ON OPPOSITE SIDES OF LEAD  
Serial No.: Unknown Filed: Herewith  
Examiner: Unknown Group Art Unit: Unknown  
Atty. Docket No.: BDG028



COMMISSIONER FOR PATENTS  
P.O. Box 1450  
Alexandria, VA 22313-1450

**ASSIGNMENT RECORDATION COVER SHEET**

Dear Sir:

Please record the attached original Assignment.

1. Name of conveying party:

Cheng-Lien Chiang

2. Name and address of receiving party:

Bridge Semiconductor Corporation  
3<sup>rd</sup> Floor, 157 Li-Te Road  
Peitou District  
Taipei, Taiwan 112

3. Nature of conveyance:

Assignment

The execution date of the Assignment is December 19, 2004.

01/10/2005 870M11 00000154 502178 11021313

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**PATENT**  
**REEL: 016130 FRAME: 0201**

4. Application number(s) or patent number(s)

This Assignment is being filed together with a new patent application. The execution date of the application is December 19, 2004.

5. Name and address of party to whom correspondence should be mailed:

David M. Sigmond  
2440 Andrew Drive  
Superior, Colorado 80027

(303) 554-8371

6. Total number of applications and patents involved: 1.

7. Total fee under 37 C.F.R. § 1.21(h): \$40.

8. Method of Payment:

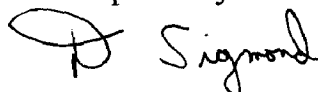
Charge the \$40 to Deposit Account No. 502178/BDG028 and charge any underpayment or credit any overpayment to this Account.

9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Total number of pages including cover sheet, attachments and document: 3.

Respectfully submitted,



David M. Sigmond  
Attorney for Applicant  
Reg. No. 34,013  
(303) 554-8371  
(303) 554-8667 (fax)

Date: Dec 22, 2004

## ASSIGNMENT

WHEREAS, I, CHENG-LIEN CHIANG of Taipei, Taiwan, have invented a certain new and useful invention entitled THREE-DIMENSIONAL STACKED SEMICONDUCTOR PACKAGE WITH CHIPS ON OPPOSITE SIDES OF LEAD, for which an application for Letters Patent of the United States has been prepared for filing, said application being identified as Attorney Docket No. BDG028;

NOW THEREFORE, be it known that I, the said inventor, for and in consideration of certain good and valuable consideration, the sufficiency and receipt of which is hereby acknowledged, at the request of the assignee do sell, assign and transfer unto said assignee, BRIDGE SEMICONDUCTOR CORPORATION, a Taiwan Corporation having a place of business at 3<sup>rd</sup> Floor, 157 Li-Te Road, Peitou District, Taipei, Taiwan 112, its successors, legal representatives and assigns, the aforesaid application for the territory of the United States of America and all continuation, divisional, continuation-in-part and reissue applications, all patent applications in foreign countries, all applications pursuant to the Patent Cooperation Treaty, and all applications for extension filed or to be filed for the invention, and all Letters Patent, Invention Registrations, Utility Models, Extensions or Reissues, Reexaminations and other patent rights, obtained for the invention in the United States or any other country; I also assign any right, title or interest in and to the invention which has not already been transferred to the assignee; I warrant that I have made no assignment of the invention, application or patent therefor to a party other than BRIDGE SEMICONDUCTOR CORPORATION and I am under no obligation to make and shall not make any assignment of the invention, application, or patent therefor to any other party; and I further agree to cooperate with the assignee hereunder in obtaining, sustaining and enforcing of any and all such Letters Patent and patent rights and in confirming the assignee's exclusive ownership of the invention, without further consideration, but at the expense of said assignee.

The Commissioner of Patents is hereby authorized and requested to issue the Letters Patent solely in accordance with the terms of this Assignment to BRIDGE SEMICONDUCTOR CORPORATION, its successors, legal representatives and assigns, as the assignee of the entire right, title and interest therein.

IN WITNESS WHEREOF, the party hereto has executed this Assignment as of the date indicated hereunder.

Date: Dec, 19, 2004

By: Cheng-Lien Chiang  
CHENG-LIEN CHIANG